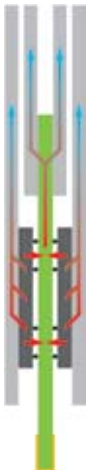




TW3X4G1333C9DHX

The TW3X4G1333C9DHX is a 4096MByte matched pair of DDR3 SDRAM DIMMs built using Corsair's latest high performance heat sink with Dual-Path Heat Xchange (DHX) technology. This part delivers outstanding performance in the latest generation of dual-channel DDR3-based motherboards. It has been tested extensively in popular DDR3 motherboards to ensure compatibility and performance at its rated speed. This memory has been verified to operate at 1333MHz at the low latencies of 9-9-9-24.



Dual-Path Heat Xchange Diagram

- Optimized fins to maximize ambient airflow through the module array
- Extruded aluminum heat sinks to maximize convective heat dissipation
- Dedicated PCB heat sink



TEST SPECS

- ▶ Each module pair is tested together at 1333MHz
- ▶ Tested and packaged in pairs
 - ▶ Packaged together immediately following system test
- ▶ Tested together at 1333MHz, Vdim = 1.70V, at latency settings of 9-9-9-24
- ▶ SPD programmed at:
 - ▶ JEDEC standard 9-9-9-24 values at 1333MHz

FEATURES

- ▶ 4096 Megabytes of DDR3 memory
 - ▶ Two matched CM3X2G1333C9DHX modules
- ▶ Using DHX technology providing maximum cooling
- ▶ 100% tested at 1333MHz in high performance DDR3 motherboards
- ▶ Lifetime warranty

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Those users installing 4GB or more of memory may notice the total amount of available memory being less than 4GB. The amount available depends on the system configuration and the way the operating system addresses physical memory. Every part is tested in Corsair's factory at 1333MHz, but your actual results may vary depending on the overclocking margin of your CPU and motherboard. Newer motherboards may be used for production test as they become available. Corsair may periodically update the part with newer RAM revisions of same or greater performance. RAM used on the module may change without notice. © April 2008 Corsair Memory, Inc.